

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Joseph M. Milewski and : Art Unit:  
Charles G. Woychik : Examiner:  
Serial No.: To Be Assigned :  
Filed: Herewith :  
For: LOW TEMPERATURE SOLDER :  
CHIP ATTACH STRUCTURE :

**DIVISIONAL APPLICATION OF:**

Applicants: Joseph Milewski and : Art Unit: 1725  
Charles G. Woychik : Examiner: K. Stoner  
Serial No.: 08/815,656 :  
Filed: March 13, 1997 :  
For: PROCESS TO PRODUCE A :  
HIGH TEMPERATURE :  
INTERCONNECTION :

**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

S I R :

Before examining the application first identified above, please  
amend that application as follows.

**IN THE TITLE:**

Please delete the title in its entirety and substitute therefor:

LOW TEMPERATURE SOLDER CHIP ATTACH STRUCTURE.

IN THE SPECIFICATION:

On page 1, before "FIELD OF THE INVENTION," Insert the following paragraph:

This application is a divisional of U.S. Patent Application Serial Number 08/815,656, filed on March 13, 1997, which has been allowed.

IN THE CLAIMS:

Please cancel claims 1-10.

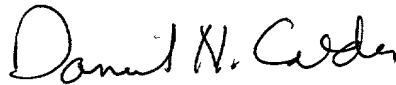
100444-100000

REMARKS

This is a divisional application of patent application Serial Number 08/815,656. The title and the specification have been amended. Claims 1-10 have been cancelled. Claims 11-19 remain and these claims are presented for examination.

Respectfully submitted,

RATNER & PRESTIA



Daniel N. Calder, Reg. No. 27,424  
Attorney for Applicants

DNC/pb

Attachment: Version with Markings to Show Changes Made

Dated: November 2, 2001

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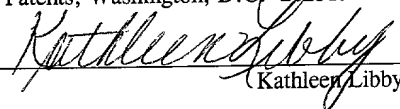
Valley Forge, PA 19482-0980

(610) 407-0700

The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. **09-0457 (IBM Corporation)** of any fees associated with this communication.

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Date of Deposit: November 2, 2001

I hereby certify that this paper and fee is being deposited, under 37 C.F.R. § 1.10 and with sufficient postage, using the "Express Mail Post Office to Addressee" service of the United States Postal Service on the date indicated above and that the deposit is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

  
(Kathleen Libby)

VERSION WITH MARKINGS TO SHOW CHANGES MADEIN THE TITLE:

[PROCESS TO PRODUCE A HIGH TEMPERATURE  
INTERCONNECTION] LOW TEMPERATURE SOLDER CHIP ATTACH  
STRUCTURE.

IN THE SPECIFICATION:

Insert before the first line of the specification --This application  
is a divisional of U.S. Patent Application Serial Number 08/815,656, filed on  
March 13, 1997, which has been allowed.--

IN THE CLAIMS:

Claims 1-10 have been cancelled.

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